

Symbol	Typ	Titel
H	Sektion	SECTION H — ELECTRICITY
H05	Klasse	ELECTRIC TECHNIQUES NOT OTHERWISE PROVIDED FOR
H05K	Unterklasse	PRINTED CIRCUITS; CASINGS OR CONSTRUCTIONAL DETAILS OF ELECTRIC APPARATUS; MANUFACTURE OF ASSEMBLAGES OF ELECTRICAL COMPONENTS (details of instruments or comparable details of other apparatus not otherwise provided for G12B; thin-film or thick-film circuits H01L 27/01, H01L 27/13; non-printed means for electric connections to or between printed circuits H01R; casings for, or constructional details of, particular types of apparatus, <u>see</u> the relevant subclasses; processes involving only a single technical art, e.g. heating, spraying, for which provision exists elsewhere, <u>see</u> the relevant classes)
H05K 1/00	Hauptgruppe	Printed circuits (assemblies of a plurality of individual semiconductor or solid state devices H01L 25/00; devices consisting of a plurality of solid state components formed in or on a common substrate, e.g. integrated circuits, thin-film or thick-film circuits, H01L 27/00)
H05K 1/02	1-Punkt Untergruppe	. Details
H05K 1/03	2-Punkt Untergruppe	. . Use of materials for the substrate [3]
H05K 1/05	3-Punkt Untergruppe	. . . Insulated metal substrate [3]
H05K 1/09	2-Punkt Untergruppe	. . Use of materials for the metallic pattern [3]
H05K 1/11	2-Punkt Untergruppe	. . Printed elements for providing electric connections to or between printed circuits [3]
H05K 1/14	2-Punkt Untergruppe	. . Structural association of two or more printed circuits (providing electric connection to or between printed circuits H05K 1/11, H01R 12/00)
H05K 1/16	1-Punkt Untergruppe	. incorporating printed electric components, e.g. printed resistor, capacitor, inductor
H05K 1/18	1-Punkt Untergruppe	. Printed circuits structurally associated with non-printed electric components (H05K 1/16 takes precedence)
H05K 3/00	Hauptgruppe	Apparatus or processes for manufacturing printed circuits (photomechanical production of textured or patterned surfaces, materials or originals therefor, apparatus specially adapted therefor, in general G03F; involving the manufacture of semiconductor devices H01L) [3]
H05K 3/02	1-Punkt Untergruppe	. in which the conductive material is applied to the surface of the insulating support and is thereafter removed from such areas of the surface which are not intended for current conducting or shielding
H05K 3/04	2-Punkt Untergruppe	. . the conductive material being removed mechanically, e.g. by punching
H05K 3/06	2-Punkt Untergruppe	. . the conductive material being removed chemically or electrolytically, e.g. by photo-etch process
H05K 3/07	3-Punkt Untergruppe	. . . being removed electrolytically [3]
H05K 3/08	2-Punkt Untergruppe	. . the conductive material being removed by electric discharge, e.g. by spark erosion
H05K 3/10	1-Punkt Untergruppe	. in which conductive material is applied to the insulating support in such a manner as to form the desired conductive pattern
H05K 3/12	2-Punkt Untergruppe	. . using printing techniques to apply the conductive material
H05K 3/14	2-Punkt Untergruppe	. . using spraying techniques to apply the conductive material
H05K 3/16	3-Punkt Untergruppe	. . . by cathodic sputtering
H05K 3/18	2-Punkt Untergruppe	. . using precipitation techniques to apply the conductive material
H05K 3/20	2-Punkt Untergruppe	. . by affixing prefabricated conductor pattern

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H05K 3/22	1-Punkt Untergruppe	. Secondary treatment of printed circuits
H05K 3/24	2-Punkt Untergruppe	. . Reinforcing of the conductive pattern
H05K 3/26	2-Punkt Untergruppe	. . Cleaning or polishing of the conductive pattern
H05K 3/28	2-Punkt Untergruppe	. . Applying non-metallic protective coatings
H05K 3/30	1-Punkt Untergruppe	. Assembling printed circuits with electric components, e.g. with resistor
H05K 3/32	2-Punkt Untergruppe	. . electrically connecting electric components or wires to printed circuits
H05K 3/34	3-Punkt Untergruppe	. . . by soldering
H05K 3/36	1-Punkt Untergruppe	. Assembling printed circuits with other printed circuits
H05K 3/38	1-Punkt Untergruppe	. Improvement of the adhesion between the insulating substrate and the metal [3]
H05K 3/40	1-Punkt Untergruppe	. Forming printed elements for providing electric connections to or between printed circuits [3]
H05K 3/42	2-Punkt Untergruppe	. . Plated through-holes [3]
H05K 3/44	1-Punkt Untergruppe	. Manufacturing insulated metal core circuits [3]
H05K 3/46	1-Punkt Untergruppe	. Manufacturing multi-layer circuits [3]
H05K 5/00	Hauptgruppe	Casings, cabinets or drawers for electric apparatus (in general A47B; radio receiver cabinets H04B 1/08; television receiver cabinets H04N 5/64)
H05K 5/02	1-Punkt Untergruppe	. Details
H05K 5/03	2-Punkt Untergruppe	. . Covers
H05K 5/04	1-Punkt Untergruppe	. Metal casings
H05K 5/06	1-Punkt Untergruppe	. Hermetically-sealed casings
H05K 7/00	Hauptgruppe	Constructional details common to different types of electric apparatus (casings, cabinets, drawers H05K 5/00)
H05K 7/02	1-Punkt Untergruppe	. Arrangements of circuit components or wiring on supporting structure
H05K 7/04	2-Punkt Untergruppe	. . on conductive chassis
H05K 7/06	2-Punkt Untergruppe	. . on insulating boards
H05K 7/08	3-Punkt Untergruppe	. . . on perforated boards
H05K 7/10	2-Punkt Untergruppe	. . Plug-in assemblages of components
H05K 7/12	2-Punkt Untergruppe	. . Resilient or clamping means for holding component to structure (holding two-part couplings together H01R 13/00)
H05K 7/14	1-Punkt Untergruppe	. Mounting supporting structure in casing or on frame or rack
H05K 7/16	2-Punkt Untergruppe	. . on hinges or pivots
H05K 7/18	1-Punkt Untergruppe	. Construction of rack or frame
H05K 7/20	1-Punkt Untergruppe	. Modifications to facilitate cooling, ventilating, or heating
H05K 9/00	Hauptgruppe	Screening of apparatus or components against electric or magnetic fields (devices for absorbing radiation from an aerial H01Q 17/00)
H05K 10/00	Hauptgruppe	Arrangements for improving the operating reliability of electronic equipment, e.g. by providing a similar stand-by unit

Symbol	Typ	Titel
H05K 11/00	Hauptgruppe	Combinations of a radio or television receiver with apparatus having a different main function
H05K 11/02	1-Punkt Untergruppe	. with vehicles
H05K 13/00	Hauptgruppe	Apparatus or processes specially adapted for manufacturing or adjusting assemblages of electric components
H05K 13/02	1-Punkt Untergruppe	. Feeding of components (in general B65G)
H05K 13/04	1-Punkt Untergruppe	. Mounting of components
H05K 13/06	1-Punkt Untergruppe	. Wiring by machine
H05K 13/08	1-Punkt Untergruppe	. Monitoring manufacture of assemblages